

IN THE CLAIMS

Please amend the claims as follows.

1-20. Canceled

- OK to Enter 9/29/04
21. (New) An electronic assembly comprising:  
a substrate;  
an integrated circuit mounted on the substrate; and  
a heat sink thermally coupled to the integrated circuit, the heat sink including a thermally conductive core having an outer surface and a plurality of non-planar helical fins extending from the outer surface of the core, the non-planar helical fins being oriented at an angle substantially between 30 and 60 degrees relative to a longitudinal axis of the heat sink; and  
a fan having a longitudinal axis, the longitudinal axis of the fan being substantially aligned with the longitudinal axis of the heat sink, the fan including an impeller having a plurality of blades that create an airflow as the impeller rotates, the airflow generated by the plurality of blades being oriented at substantially the same angle relative to the longitudinal axis of the fan as the angle of the non-planar helical fins is relative to the longitudinal axis of the heat sink.
22. (New) The heat sink of claim 21 wherein the non-planar helical fins are oriented at an angle of about 45 degrees relative to the longitudinal axis of the heat sink.
23. (New) The heat sink of claim 21 wherein the core is a cylindrical rod.
24. (New) The heat sink of claim 21 wherein the non-planar helical fins spiral around the thermally conductive core at a substantially uniform pitch.